

ABSTRACT OF THE DISCLOSURE

A connection component for use in making microelectronic element assemblies which has peelable leads that are formed on a dielectric support structure. One end of each lead is permanently connected to the support structure and the opposite end of the lead is releasably connected to the support structure. When the releasable end of the lead is bonded to a contact on a semiconductor chip, the releasable end of the lead can be peeled from the support structure such that the chip may be moved away from the support structure. A compliant layer may be disposed between the chip and the support structure. If a compliant material is injected between the chip and the support structure to form the compliant layer, the compliant material will lift the chip away from the support structure and facilitate the peeling of the leads from the support structure.

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